晶圓廠 CENTURA P.M. 程序

Wafer factory CENTURA P.M. procedure

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CENTURA P.M. 程序

壹、目的 motivation：

定期檢查機台狀況，以維持機台正常運作。

To check the machine function regularly and maintain the machine to operate properly.

貳、適用時機、範圍及規則 Adequate timing, scope and regulation：

適用時機：CENTURA 5200：20000±2000片，機臺異常須 MAINTENANCE 時。

Adequate timing: CENTURA 5200：20000±2000 pieces , the machine is abnormal and need to do maintenance.

適用範圍：APPLIED MATERIAL CENTURA MACHINE 。

Adequate scope: APPLIED MATERIAL CENTURA MACHINE

執行規則：大 PM CLEAN CHAMBER。

Implement regulation: large PM CLEAN CHAMBER

參、材料 materials：

IPA、DI水、H2O2、無塵布、手套、口罩、大白布、***護目鏡***。

IPA、DI water, H2O2 , dust free fabric, gloves, face mask, large white fabric, ***goggles***

肆、工具 tools：

L 型板手、(+)(-)起子、真空吸 塵軟管、半面式空氣濾清呼吸防護面罩、AIR GUN。

L shape wrench, (+)(-) screwer, vacuum dust soft tube, half face style air filter breath protection mask, air gun

伍、注意事項 notice：

1. 參考各檢查項目之注意事項。

Refer to every check item’ s notice issues

2. QUARTERLY P.M.項目必須包括 MONTHLY P.M.項目

   QUARTERLY P.M. items must include MONTHLY P.M. items

   (參考 PRECISION 5000 MONTHLY P.M. PROCEDURE)。

   (refer to PRECISION 5000 MONTHLY P.M. PROCEDURE)

3. PM 時須二人以上(含二人)夥同做業。

   Require more than 2 persons (at least 2 persons) for PM operating.

4. 各 CHAMBER PM 後需將 T/C WAFER 放於 SUSCEPTOR 上，SUSCEPTOR 昇至330 MIL PROCESS 位CHAMBER的 AR-GAS；AR-PURGE；AR-SS 設定 300 SCC PURGE 待溫度穩定後將其溫度記錄於 PM 表格中。

   After every CHAMBER PM, it need to place T/C WAFER on the SUSCEPTOR, when SUSCEPTOR rise to 330 MIL PROCESS in CHAMBER’ s AR-GAS; AR-PURGE；AR-SS set 300 SCC PURGE, and awaiting the temperature remain stable and record the temperature figures in PM file.

5. LOADLOCK CHAMBER測漏時，BUFFER CHAMBER 需先VENT至常壓，同時LOADLOCK CHAMBER 並做CYCLE PURGE後PUMPDOWN至底壓，做1分鐘LEAKAGE測漏。

   When LOADLOCK CHAMBER leak hunting, BUFFER CHAMBER should be VENT to regular pressure and in the meantime, LOADLOCK CHAMBER and do cycle. After PURGE and then PUMPDOWN to bottom pressure and apply LEAKAGE leak hunting for 1 min.

6. BUFFER CHAMBER測漏時，LOADLOCK CHAMBER需先VENT至常壓，同時將LOADLOCK CHAMBER DOOR OPEN,另外4個 PROCESS CHAMBER的 AR-GAS ; AR-PURGE ; AR-SS 設定 300 SCC 作CHAMBER PURGE，BUFFER CHAMBER 並做CYCLE PURGE後PUMPDOWN至底壓，做1分鐘LEAKAGE測漏。

   When BUFFER CHAMBER leak hunting, LOADLOCK CHAMBER need to be VENT to regular

pressure. In the meantime, LOADLOCK CHAMBER DOOR OPEN, and other 4 PROCESS CHAMBER’ s AR-GAS；AR-PURGE；AR-SS set 300 SCC and do CHAMBER PURGE, BUFFER CHAMBER and apply CYCLE PURGE and then PUMPDOWN to bottom pressure. Then, apply LEAKAGE leak hunting for 1 min.

陸、安全事項security issues：

防護用具之穿戴 protection equipment and wearable：

1. 半面式空氣濾清呼吸防護面罩：在作業環境中防止空氣中有害物質經過呼吸 而造成嚴重危險，可達到過濾空氣之效果。

   Half face style air filter breath protection mask: to prohibit breath into dangerous materials and occur damage to physical health and the mask will filter clean air.

2. 防護手套：防止有害物質直接觸及到皮膚表面。

   Protection gloves: to prevent dangerous materials contact to human’ s skin directly.

3. 使用化學品,應穿戴防護器具。

   Use chemicals, wear protective equipment.

4. 使用 Air Gun 及拆裝 Quartz Window，應配戴護目鏡。

   Goggles should be worn when using the Air Gun and removing and installing Quartz Window .

5. 拆裝 QUARTZ WINDOW 時，請使用護墊保護背部及腰部。

When disassembling and installing the QUARTZ WINDOW, please use the pads to protect the back and waist.

6. 使用 H2O2 Clean parts 時，需拿至 IMP 抽氣工作台上執行 clean，並穿戴黃色乳膠手套。

When using H2O2 Clean parts, take them to the IMP extraction workbench for cleaning and wear yellow latex gloves.

柒、PM 步驟 PM procedure：

一、CHAMBER MAINTENANCE

1. 設備於 PM 降溫前 SIH4 gas pump down→ 關 SIH4 MFC 上方 manual valve，空測 SIH4 gas line PTC (ARSS：300、SUSCEPTOR：process position、時間：3 min)，並於檢測後紀錄 PTC 顆數，若>100 顆以上，再檢測一次確認管路是否汙染，再行降溫BPM。

   Before the temperature of PM cools, SIH4 gas pump down → Manual valve above SIH4 MFC, SIH4 gas line PTC (ARSS: 300, SUSCEPTOR: process position, time: 3 min), and record the number of PTC after test, if 100 or more, once again confirm whether the pipeline is polluted, and then reduce the temperature BPM.

2. 將 SYSTEM 改為 MANUAL 選 SYSTEM → CONTROL SYSTEM 選取 AUTO MATION 改為 MANUAL，並可 發現 SYSTEM 及WAFER 欄位由藍轉白。

   Choose the SYSTEM change to MANUAL and select SYSTEM→ CONTROL SYSTEM select AUTO MATION and change to MANUAL, and then will see SYSTEM and WAFER was blue and turn to white color.

3. 將 MAINTENANCE 之CHAMBER 降溫 PURGE，先選 CONTROL SYSTEM SCREEN → CLEANING PROCESS 選取 RF CLEAN RECIPE(WSIX 1700-CLN) 作 CLEAN ACTION 2次 → 選 CHAMBER SERVICE 設定 MODIFY TEMP 降溫 → 選 MONITOR GAS PANEL 設定 AR-GAS；AR-PURGE；AR-SS GAS 各通 800~900 SCCM PURGE CHAMBER。

   To cool down the CHAMBER of MAINTENANCE, select CONTROL SYSTEM SCREEN → CLEANING PROCESS, select RF CLEAN RECIPE (WSIX 1700-CLN) for CLEAN ACTION twice → select CHAMBER SERVICE, set MODIFY TEMP to cool down → select MONITOR GAS PANEL, set AR-GAS; AR- PURGE; AR-SS GAS each pass 800~900 SCCM PURGE CHAMBER .

4. Wsix機台降溫前須將該機台的 CHAMBER的CHAMBER LID 的循環水快速接頭拔掉 CHECK機台是否會LAMP OFF 而降溫ALARM; 其目的是為確認機台是否FUNCTION正常，若檢視正常，既復歸CHAMBER LID 冷卻循環水的INTERLOCK SENSOR。

   Before the temp decrease of Wsix machine, it should be plug out the cycling water of machine' s CHAMBER LID and check if the machine will be LAMP OFF, decrease temp and then alarm. The motivation is to confirm the machine function is operating normal.

5. CHAMBER TEMP 降溫至 100℃ 以下 → 選 MONITOR GAS PANEL 設定 CLOSE ALL GAS → 選 MONITOR CHAMBER 設定 CLOSE FORLINE VALVE → OPEN N2 VALVE 通入 PROCESS CHAMBER → VENT CHAMBER 至 ATM 後 CLOSE N2 VALVE。

   CHAMBER TEMP cool down below 100°C → select MONITOR GAS PANEL to set CLOSE ALL GAS → select MONITOR CHAMBER to set CLOSE FORLINE VALVE → OPEN N2 VALVE open PROCESS CHAMBER → VENT CHAMBER to ATM and then CLOSE N2 VALVE .

6. MAINTENANCE 前將備妥之半面式空氣濾清呼吸防護面罩戴上，GUN BELLOW 上 AIR MODULE 並OPEN AIR，OPEN CHAMBER COVER，接上備妥之 LOW VACUUM 對準 CHAMBER 內，使其吸去廢氣 (OUT GASING)。

   Before MAINTENANCE, you should wear half face style air filter breath protection mask first, GUN BELLOW on AIR MODULE and OPEN AIR，OPEN CHAMBER COVER, and connect LOW VACUUM into CHAMBER, and to make it will vacuum the waste gas(OUT GASING).

7. 以英制板手拆下 GAS BOX ASSEMBLY 置於大白布上，SEE PROCESS KIT MODULE ，先以沾染 H2O2之無塵布擦拭拆下 GAS BOX PARTS，再次以 IPA 擦拭一次 OK，並以備妥之 AIR

GUN 吹乾擦拭過之 GAS ASSEMBLY PARTS。

To take down GAS BOX ASSEMBLY by British system wrench and place it on the large white fabric, SEE PROCESS KIT MODULE ，use the dust free fabric to stain with H2O2 in advance and to take down GAS BOX PARTS, wipe by IPA and then dry the GAS ASSEMBLY PARTS by AIR GUN.

** 注意：(1) Tube, Gas Feed 若不潔，則須更換。

(2) Manifold, Gas WSi內部管路須clean，以保氣流暢通。

** notice: (1) If the Tube, Gas Feed are unclean and it should be change to new one.

(2) Manifold, Gas WSi inner tubes should be clean and keep freely flowing.

8. 以相對之 SEQUENCE ASEMBLY SEE PROCESS KIT MODULE → GAS BOX ASSEMBLY OK。

Relative SEQUENCE ASEMBLY SEE PROCESS KIT MODULE → GAS BOX ASSEMBLY OK

9. 將LAMP電源及冷卻水接頭拔除後將LAMP拆下，檢查LAMP是否有壞損如有壞損則更換。使用英制板手將QUARTZ WINDOW拆除並更換。

To plug out LAMP power and cooling water connect in advance and then to take down LAMP. And check LAMP to see if any damage on it and if so, it should be replace for new one. For replacement, it should be take down and change QUARTZ WINDOW by British system wrench.

10. 以相對方式將QUARTZ WINDOW及LAMP回裝。

To install the QUARTZ WINDOW and LAMP by relative method.

11. 至1F將BURN BOX上蓋螺絲拆下後將上蓋打開，用LOW VACCUM CLEAN內部後回裝，並檢視 PM 該 CHAMBER PUMP OIL LEVEL 是否正常(全程佩帶半面式空氣濾清呼吸防護面罩)。

To 1F, take down the screw on the cover of BURN BOX and open the cover, use the LOW VACCUM CLEAN inside and reinstall and check the PM’ s CHAMBER PUMP OIL LEVEL

to see if it operate normal(wear with half face style air filter breath protection mask for entire procedure)

12. 完成 CHAMBER MAINTENANCE 後，收拾使用過沾染 POWDER (沉積物) 的無塵布、手套、並確認是否為腐蝕類廢棄物，加以區分後以透明夾鏈袋包好密封繫實袋口，置放於小方格腐蝕性垃圾桶。另 LOW VACUUM、AIR GUN、半面式空氣濾清呼吸防護面罩收回擺放於其定位。
After complete the CHAMBER MAINTENANCE, clean the used and stained with POWDER(sediments) dust free fabric and gloves and check if they are corrupt type hazardous waste. To separate them and sealing by transparent ziplock bag and place them in square shape corrupt type waste basket. For LOW VACUUM、AIR GUN and half face style air filter breath protection mask should be recycling and place in original area.
13. 後續將 CHAMBER SUSCEPTOR 升至PROCESS POSITION，放置 T/C WAFER於SUSCEPTOR 上，CLOSE CHAMBER ASSEMBLY→OPEN FORLINE 抽真空→CHAMBER SERVICE 升溫至 400度，ARGON OPEN 至300 SCCM， 待約10 MINUTE 以T/C WAFER MONITOR ACTUAL TEMPERATURE，(並於EMS TABLE 上作實際溫度的記錄)，而後降溫至100度 VENT CHAMBER 取出 T/C WAFER，此動作即完成 MONITOR CHAMBER TEMPERATURE(另將取出之 T/C WAFER擺回定位) 。
And then rise the CHAMBER SUSCEPTOR to PROCESS POSITION, place T/C WAFER on SUSCEPTOR, CLOSE CHAMBER ASSEMBLY→OPEN FORLINE vacuum→CHAMBER SERVICE temp rise to 400 degree, ARGON OPEN
to 300 SCCM, awaiting for 10 MINUTE by T/C WAFER MONITOR ACTUAL TEMPERATURE, (and record the actual temp on EMS TABLE), and then temp decrease to 100 degree VENT CHAMBER and take out T/C WAFER, the motion is complete MONITOR CHAMBER TEMPERATURE(and take out T/C WAFER and place it the original

area)

14. 將BUFFER CHAMBER VENT後以沾IPA之無塵布CLEAN FLAT CHAMBER,並檢查LIFT ARM及ORIENT PAD上O-RING是否損壞,破損或變形則需更換。

After BUFFER CHAMBER VENT, to CLEAN FLAT CHAMBER by dust free fabric that stained with IPA and check O-RING on the LIFT ARM and ORIENT PAD. If any damage or deform of O-RING and it should be replacement.

二、LOADLOCK CHAMBER TRANSFER 的檢查與調整

The inspection and adjustment on LOADLOCK CHAMBER TRANSFER

1. 將 SYSTEM 改為" MANUAL"選 SYSTEM → CONTROL SYSTEM，選取 AUTOMATIC 改為 MANUAL，並可發現" SYSTEM"及" WAFER"欄位由藍轉白。

Choose SYSTEM, change to" MANUAL"and select SYSTEM→ CONTROL SYSTEM, select AUTOMATIC and change to MANUAL. And then will see " SYSTEM"and " WAFER"was blue and turn to white color.

2. 將系統做 HOME（WAFER MONITER HANDLER HOME ALL ROBOTAXES）BUFFER CHAMBER VENT（WAFER → CONTROL HANDLER → VENT BUFFLE → OPEN VENT VALVE)。

Make the system to HOME(WAFER MONITER HANDLER HOME ALL ROBOTAXES)BUFFER CHAMBER VENT（WAFER → CONTROL HANDLER → VENT BUFFLE → OPEN VENT VALVE)。

3. 設定 SLIT VALVE INTERLOCK，使其能在 ATM 下開啟。

To set SLIT VALVE INTERLOCK and make it open under ATM.

4. MISC → SYSTEM CONFIGURATION → CONFIGURE SYSTEM 選取 VACUUM SENSOR 處將" CHECK"改為" IGNORE"。

MISC → SYSTEM CONFIGURATION → CONFIGURE SYSTEM select VACUUM SENSOR and choose" CHECK" And change to " IGNORE"。

5. MISC → MAINTEMANCE → DIGITAL I/O，將 DI/DO BOARD 上之 2-21，設定其 ENABLE"1"。

MISC → MAINTEMANCE → DIGITAL I/O， select DI/DO BOARD and 2-21，to set the ENABLE"1"

6. WAFER MONITOR HANDLER 將 LOADLOCK X 之 SLIT VALVE 由" CLOSE" 改為" OPEN" 。

WAFER MONITOR HANDLER choose LOADLOCK X' s SLIT VALVE and choose" CLOSE" change to" OPEN" 。

7. 設定使 ROBOT 能以慢速度做檢查 MIS → CONFIGURE SYSTEM → FUTURE CONFIGURE 選取 LOADER OPTIONS 之 BIT29，將其改為 ON。

Setting the ROBOT to check MIS by slow speed→ CONFIGURE SYSTEM → FUTURE CONFIGURE select LOADER OPTIONS' s BIT29，and change it to ON。

8. CHECK BLADE LEVELING。

8.1 WAFER → MONITOR HANDLER → ROTATION 選取" CASS X INS POS" 。

WAFER → MONITOR HANDLER → ROTATION select" CASS X INS POS" 。

8.2 EXTENSION 選取" CHAMBER，DROP。

EXTENSION " select CHAMBER，DROP。

8.3 以水平儀放至於 BLAND CHECK BLADF 是否平整若 BLADE LEVELING不好，請調整 BLADE LEVELING SCREW。

To put the on BLAND CHECK BLADF and to see if it is level. If the BLADE LEVELING is not good and please adjust BLADE LEVELING SCREW.

8.4 將 EXTENSIN 改為”ZERO POSITION”。

Choose EXTENSIN and change to”ZERO POSITION”

8.5 將 DUMMY WAFER 放置於 CASSETTE 之 SLOT1、2、12、13、24、25 並將 CASSETTE 放置於 INDEXER 上。

To place DUMMY WAFER on CASSETTE’s SLOT1、2、12、13、24、25 and place CASSETTE on the INDEXER

8.6 WAFER → MONITOR HANDLER，將 CASS 轉至”IN”。

WAFER → MONITOR HANDLER，turn CASS to”IN”

9. CHECK CASSETTE SLOT SPACING。

9.1 WAFER → MONITOR HANDLER → CASS ELEVATOR → REQ SLOT：2 → TO SLOT BASE。使 CASS 移至 SLOT2 。

WAFER → MONITOR HANDLER → CASS ELEVATOR → REQ SLOT：2 → TO SLOT BASE。make CASS move to SLOT2

9.2 WAFER → MONITOR HANDLER → EXTENSION DIRECT CONTROL → OUT：10000。使 BLADE 伸出 SLIT VALVE，於 SLOT1、SLOT2 。

WAFER → MONITOR HANDLER → EXTENSION DIRECT CONTROL → OUT：10000。To make BLADE extend to SLIT VALVE on the SLOT1、SLOT2 。

9.3 同 9.2 每次 OUT 1000，確定 BLADE 在 SLOT1、SLOT2 。

Same as step 9.2 everytime OUT 1000，confirm BLADE on the SLOT1、SLOT2 。

9.4 若 BLADE 在 CASS 內有 FRONT-TO-BACK 或 SIDE-TO-SIDE 之斜，請適當調整 INDEX之 LEVELING SCREW。

if any descend of BLADE is in the inner CASS FRONT-TO-BACK or SIDE-TO-SIDE ，please adequately adjust INDEX‘s LEVELING SCREW.

9.5 若 BLADE 不在 SLOT 之間，而 INDEX LEVELING 已 OK 則請將 CASS ELEVATOR 做 DIRECT CONTROL。

If the BLADE is not within SLOT, and INDEX LEVELING is already OK, then, please make CASS ELEVATOR to do DIRECT CONTROL.

9.6 請確定 BLADE 在 SLOT1、2 之間記錄 CASS ELEVATOR 之 SETP(A)。

Please confirm BLADE is between SLOT1、2 and record CASS ELEVATOR’ s SETP(A)

9.7 選取 CASS ELEVATOR → REQ SLOT：2 → TO SLOT DELTA。使 WAFER可以恰巧落在 BLADE 之 FRONT SHOE。若 HAND-OFF 並不佳，請做” TO SLOT BASE” ，並將 EXTENSION 及 ROTATION 做 DIRECT CONTROL(EXIT:IN OR OUT，ROT：CW OR CCW) 並做本步驟確定。

To select CASS ELEVATOR → REQ SLOT：2 → TO SLOT DELTA. To make WAFER will drop down on the FRONT SHOE of BLADE. If HAND-OFF is not good, please do” TO SLOT BASE” ，and make EXTENSION and ROTATION to do DIRECT CONTROL(EXIT:IN OR OUT，ROT：CW OR CCW) and apply this step to confirm it.

9.8 將 EXTENSION 及 ROTATION 之值輸入 CASS X PICK 及 DROP 內（MONITOR HANDLER B/ROBOT CALIB）(REF：FG7)。

For figures of EXTENSION and ROTATION to entry into CASS X PICK and DROP （MONITOR HANDLER B/ROBOT CALIB）(REF：FG7)。

9.9 將 CASS 移至 SLOT2 之” SLOT BASE” ，而 EXT 做” ZERO POS 。

Make CASS move to SLOT2’ s” SLOT BASE” ，and EXT do ” ZERO POS

9.10 CASS ELEVATOR → REQ SLOT：25 → TO SLOT BASE。

9.11 以 9.2~9.5 之方法使 BLADE 在 SLOT 24,25 之間。

To apply the methods of 9.2~9.5 and make BLADE will be between SLOT 24, and 25。

9.12 確定 BLADE 在 SLOT24，25 間後，記錄其 CASS ELEVATOR 之 STER(B) 。

After confirm the BLADE is in SLOT24，25 and record CASS ELEVATOR’ s STER(B)

9.13 將 BOTTOM SLOT OFFSET 及 SLOT SPACING 輸入至 CASS CALIB(SLOT SPACING =(B-A)/23，BOTTOM SLOT OFFSET=A+SLOT SPAING)。

To make BOTTOM SLOT OFFSET and SLOT SPACING and enter to CASS CALIB(SLOT SPACING=(B-A)/23，BOTTOM SLOT OFFSET=A+SLOT SPAING)。

9.14 將 EXT 做 ZERO POS：以 9.1~9.9 反覆確定，SLOT2，13，25 時BLADE 是否會刮傷 WAFER。

To make EXT do ZERO POS：to apply with 9.1~9.9 to reconfirm that when SLOT2，13，25, and if BLADE will scratch WAFER。

9.15 關閉 SLIT VALVE，BIT29"OFF" 於 CASS上CREAT SLOT2，13，25 以SOURCE FOR MOVE 及 DESTINATION 方式 TEST。若有問題，請重覆 6,9.1~9.14；若 OK 請移去 CASSETTE。

To turn off SLIT VALVE，BIT29"OFF" in CASS on the CREAT SLOT2，13，25 by SOURCE FOR MOVE and DESTINATION method to TEST. If any abnormal，please redo 6,9.1~9.14 ；If ok and please remove CASSETTE。

9.16 以相同步驟將另一 LOADLOCK 校正 OK。

To apply same procedure and correct another LOADLOCK to OK

9.17 將操作步驟 4 之 VACUUM SECSOR 改回 "CHECK" 。

For step 4’ s VACUUM SECSOR and change it to "CHECK"

9.18 將操作步驟 5 之 DI/DO 2-21 改回 "DISABLE"(0)。

For step 5’ s DI/DO 2-21 and change it to "DISABLE"(0).

9.19 PRING B/ROBOT & CASS DATA 。

三、PROCESS CHAMBER TRANSFER 檢查與調整

PROCESS CHAMBER TRANSFER inspection and adjustment

1. 將 SYSTEM 改為”MANUAL”選 SYSTEM → CONTROL SYSTEM，選取 AUTOMATIC 改為 MANUAL。並可發現”SYSTEM”及”WAFER”欄位由藍轉白。

   Choose SYSTEM, change to”MANUAL”and select SYSTEM→ CONTROL SYSTEM, select AUTOMATIC and change to MANUAL. And then will see ”SYSTEM”and ”WAFER” were blue and turn to white color.

2. 將系統做 HOME（WAFER MONITER HANDLER HOME ALL ROBOTAXES）BUFFER CHAMBER VENT（WAFER → CONTROL HANDLER → VENT BUFFLE → OPEN VENT VALVE)。

   Make the system to HOME（WAFER MONITER HANDLER HOME ALL ROBOTAXES）BUFFER CHAMBER VENT（WAFER → CONTROL HANDLER → VENT BUFFLE → OPEN VENT VALVE)。

3. 設定 SLIT VALVE INTERLOCK，使其能在 ATM 下開啟。

   To set SLIT VALVE INTERLOCK and make it open under ATM.

4. MISC → SYSTEM CONFIGURATION → CONFIGURE SYSTEM 選取 VACUUM SENSOR 處將”CHECK”改為”IGNORE"。

   MISC → SYSTEM CONFIGURATION → CONFIGURE SYSTEM select VACUUM SENSOR and choose”CHECK”And change to ”IGNORE"。

5. MISC → MAINTEMANCE → DIGITAL I/O，將 DI/DO BOARD 上之 2-21，設定 ENABLE"1"。

   MISC → MAINTEMANCE → DIGITAL I/O， select DI/DO BOARD and 2-21，to set the ENABLE"1"

6. WAFER MONITOR HANDLER 將 LOADLOCK X 之 SLIT VALVE 由”CLOSE”改為”OPEN” 。

WAFER MONITOR HANDLER choose LOADLOCK X’ s SLIT VALVE and choose” CLOSE” change to” OPEN”

7. 設定使 ROBOT 能以慢速度做檢查 MIS → CONFIGURE SYSTEM → FUTURE CONFIGURE 選取 LOADER OPTIONS 之 BIT29，將其改為 ON。

Setting the ROBOT to check MIS by slow speed→ CONFIGURE SYSTEM → FUTURE CONFIGURE select LOADER OPTIONS’ s BIT29，and change it to ON。

8. OPEN PROCESS CHAMBER X 之 SLIT VALVE 由” CLOSE” 改為” OPEN”

OPEN PROCESS CHAMBER X ‘s SLIT VALVE choose” CLOSE” and change to” OPEN”

9. WAFER DO ORIENT

9.1 將 DUMMY WAFER 放置於 CASSETTE 之 SLOT1並將 CASSETTE 放置於 INDEXER 上。

To place DUMMY WAFER on the CASSETTE’ s SLOT1 and place CASSETTE on the INDEXER

9.2 WAFER → MONITOR HANDLER → ROTATION 選取” CASS X INS POSN” 。

WAFER → MONITOR HANDLER → ROTATION select ” CASS X INS POSN”

9.3 WAFER → MONITOR HANDLER → CASS ELEVATOR → REQ SLOT：1 → TO SLOT BASE。使 CASS 移至 SLOT1。

WAFER → MONITOR HANDLER → CASS ELEVATOR → REQ SLOT : 1 → TO SLOT BASE。To make CASS move to SLOT1

9.4 WAFER → MONITOR HANDLER → EXTENSION → TO CH PICKUP。使 BLADE 伸入 CASSETTE內。

WAFER → MONITOR HANDLER → EXTENSION → TO CH PICKUP。To make the BLADE extend into CASSETT

9.5 選取 CASS ELEVATOR → REQ SLOT：1 → TO SLOT DELTA。使 WAFER可以恰巧落在

BLADE 之 FRONT SHOE。

To select CASS ELEVATOR → REQ SLOT：1 → TO SLOT DELTA。And make WAFER will drop down on the FRONT SHOE of BLADE

9.6 WAFER → MONITOR HANDLER → EXTENSION → TO ZERO POSN。使BLADE縮回BUFFER內。

WAFER → MONITOR HANDLER → EXTENSION → TO ZERO POSN。To make BLADE retract inside of BUFFER

9.7 WAFER → MONITOR HANDLER → ROTATION 選取" CH F POSN" 。

WAFER → MONITOR HANDLER → ROTATION and select" CH F POSN"

9.8 CH F → CHAMBER SERVICE → 選取CHAMBER ON LINE FOR MAINTENANCE 改為 OFF LINE。

CH F → CHAMBER SERVICE → select CHAMBER ON LINE FOR MAINTENANCE and change to OFF LINE。

9.9 CH F → CHAMBER SERVICE → WAFER LIFT → RELEASE。使LIFTER下降至RELEASE位置。

CH F → CHAMBER SERVICE → WAFER LIFT → RELEASE。To make LIFTER decrease to RELEASE position

9.10 WAFER → MONITOR HANDLER → EXTENSION → TO CH DROP。使 BLADE 伸入CH F內。

WAFER → MONITOR HANDLER → EXTENSION → TO CH DROP。To make BLADE extend into CH F

9.11 CH F → CHAMBER SERVICE → WAFER LIFT → LIFT。使LIFT上升頂起WAFER。

CH F → CHAMBER SERVICE → WAFER LIFT → LIFT。To make LIFT arise and support WAFER .

9.12 檢視WAFER是否在LIFT中央位置。YES則跳至9.16步驟。NO則繼續下一個步驟。

To see if the WAFER is in the middle of LIFT. YES and skip to step 9.16. NO and continue next step.

9.13 CH F → CHAMBER SERVICE → WAFER LIFT → RELEASE。WAFER → MONITOR HANDLER → EXTENSION DIRECT → TO ZERO POSN。將WAFER取出至BUFFER內。

CH F → CHAMBER SERVICE → WAFER LIFT → RELEASE。WAFER → MONITOR HANDLER → EXTENSION DIREC→ TO ZERO POSN. To move out WAFER and place inside of BUFFER

9.14 WAFER → MONITOR HANDLER → B/ROBOT CALIB。更改CHAMBER F DROP之EXT & ROT參數。同時CHAMBER F PICK之EXT & ROT參數也須更改與CHAMBER F DROP參數一樣。調整WAFER前後左右位置。

WAFER → MONITOR HANDLER → B/ROBOT CALIB. To modify CHAMBER F DROP’ s EXT & ROT parameter。In the meantime, CHAMBER F PICK’ s EXT & ROT parameter should be modify same as CHAMBER F DROP. And, to minor adjust the front, back, left and right side position of WAFER.

9.15 重複9.7至9.14步驟調整到位置OK。

Redo the step 9.7 to 9.14 and adjust the place to OK position

9.16 WAFER → MONITOR HANDLER → EXTENSION→ TO ZERO POSN。

9.17 CH F → CHAMBER SERVICE → DO ORIENT。使WAFER做轉平邊。

CH F → CHAMBER SERVICE → DO ORIENT。To align WAFER to flat side.

9.18 CH F → CHAMBER SERVICE → WAFER LIFT → LIFT。WAFER → MONITOR HANDLER → EXTENSION → TO ZERO POSN。將WAFER取出至BUFFER內。

CH F → CHAMBER SERVICE → WAFER LIFT → LIFT。WAFER → MONITOR HANDLER → EXTENSION → TO ZERO POSN。 To move out WAFER and place inside BUFFER。

10. WAFER → MONITOR HANDLER → ROTATION 選取" CH X POSN" 。
    WAFER → MONITOR HANDLER → ROTATION select" CH X POSN"
11. CH X → CHAMBER SERVICE → GO TO WAFER RELEASE POS' N。使LIFT AND SUSCEPTOR移至RELEASE位置。
    CH X → CHAMBER SERVICE → GO TO WAFER RELEASE POS' N。To make LIFT AND SUSCEPTOR move to RELEASE position
12. WAFER → MONITOR HANDLER → EXTENSION→ DIRECT CONTROL → MOVE OUT BY：5000 STEPS。使 BLADE 伸出 SLIT VALVE。
    WAFER → MONITOR HANDLER → EXTENSION→ DIRECT CONTROL → MOVE OUT BY：5000 STEPS. To make BLADE extend to SLIT VALVE。
13. 同 12步驟每次 MOVE OUT BY：1000,檢視 BALDE & WAFET 是否會撞到SUSCEPTOR FINGER。若會撞到則調整SUSCEPTOR & FINGER高低位置。
    Same as step 12 every time MOVE OUT BY：1000, and inspect if the BALDE & WAFET will hit the SUSCEPTOR or FINGER. If so, please adjust the height position of SUSCEPTOR & FINGER
14. WAFER → MONITOR HANDLER → EXTENSION → TO CH DROP。使 BLADE 伸入CH X內。
    WAFER → MONITOR HANDLER → EXTENSION → TO CH DROP. To make BLADE extend inside of CH X
15. CH X → CHAMBER SERVICE → GO TO WAFER LIFT POS' N。使FINGER上升頂起WAFER。
    CH X → CHAMBER SERVICE → GO TO WAFER LIFT POS' N. To make FINGER arise and support WAFER。

16. WAFER → MONITOR HANDLER → EXTENSION → TO ZERO POSN。
17. CH X → CHAMBER SERVICE → GO TO WAFER PROCESS POS’ N。FINGER下降SUSCEPTOR上升承接WAFER。檢視WAFER是否在 SUSCEPTOR 中央的位置。YES則跳至25步驟。NO則繼續下一個步驟。

    CH X → CHAMBER SERVICE → GO TO WAFER PROCESS POS’ N。FINGER decrease SUSCEPTOR arise and support WAFER. To check if WAFER is in the middle place of SUSCEPTOR. YES and skip to step 25. NO and then continue to next step。
18. CH X → CHAMBER SERVICE → GO TO WAFER LIFT POS’ N。使FINGER上升頂起WAFER。

    CH X → CHAMBER SERVICE → GO TO WAFER LIFT POS’ N。To make FINGER arise and support WAFER。
19. WAFER → MONITOR HANDLER → EXTENSION → TO CH PICKUP。使 BLADE 伸入CH X內。

    WAFER → MONITOR HANDLER → EXTENSION → TO CH PICKUP. To make BLADE extend inside of CH X
20. CH X → CHAMBER SERVICE → GO TO WAFER RELEASE POS’ N。使WAFER放於BLEAD上。

    CH X → CHAMBER SERVICE → GO TO WAFER RELEASE POS’ N. To place WAFER on the BLEAD
21. WAFER → MONITOR HANDLER → EXTENSION → TO ZERO POSN。
22. WAFER → MONITOR HANDLER → B/ROBOT CALIB。更改CHAMBER X DROP之EXT & ROT參數。同時CHAMBER X PICK之EXT & ROT參數也須更改與CHAMBER X DROP參數一樣。調整WAFER前後左右位置。

WAFER → MONITOR HANDLER → B/ROBOT CALIB。To modify CHAMBER X DROP’ s EXT & ROT parameter。In the meantime, CHAMBER X PICK’ s EXT & ROT parameter should be modify same as parameter of CHAMBER X DROP. To adjust the front, back, left and right side position of WAFER。

23. WAFER → MONITOR HANDLER → ROTATION 選取” CH X POSN” 。使ROBOT移動至更改參數後CHAMBER X ROTATION的位置。

WAFER → MONITOR HANDLER → ROTATION select” CH X POSN” . To make ROBOT move to CHAMBER X ROTATION position with modified parameter

24. 重複14至23步驟調整到位置OK。

Redo step 14 to 23 and adjust to position ok

25. 取出WAFER。CH X → CHAMBER SERVICE → HOME LIFT AND SUSCEPTOR。

To take out WAFER。CH X → CHAMBER SERVICE → HOME LIFT AND SUSCEPTOR。

26. 將操作步驟 4 之 VACUUM SECSOR 改回 "CHECK" 。

Step 4 ‘s VACUUM SECSOR change to "CHECK" 。

27. 將操作步驟 5 之 DI/DO 2-21 改回 "DISABLE"(0)。

Step 5 ‘s DI/DO 2-21 change to "DISABLE"(0)

28. 將操作步驟 6 之 LOADLOCK X 之 SLIT VALVE 由” OPEN” 改為” CLOSE” 。

Step 6 ‘s LOADLOCK X ‘s SLIT VALVE choose ” OPEN” and change to ” CLOSE”

29. 將操作步驟 7 之 BIT29，將其改為 OFF。

Step 7 ‘s BIT29 and change to OFF

30. 將操作步驟 8 之PROCESS CHAMBER X 之 SLIT VALVE 由” OPEN” 改為” CLOSED” 。

Step 8 ‘s PROCESS CHAMBER X ‘s SLIT VALVE choose” OPEN” and change to ” CLOSED”

31. 完成 PROCESS CHAMBER TRANSFER 的檢查與調整。

Complete PROCESS CHAMBER TRANSFER’ s inspection and adjustment

四、CHAMBER RF 的校正

The correction of CHAMBER RF

1. 將 RF MATCHING BOX 處 RF 電纜的接頭旋下，接上 DUMMY LOAD 處 RF INPUT 處，OUTPUT 處接上一小段 RF 電纜再接上 RF 轉換盒，最後接上BIRD METER。

   To take down the connect of RF MATCHING BOX RF cable ，and connect DUMMY LOAD RF INPUT ，connect OUTPUT and RF cable and connect with RF switch box. Final, and connect with BIRD METER

2. 用光筆點 Misc → Chamber Parameters → RF Calibration，選擇Calibration start，此時，Current 處全部顯示 400。

   Use light pen click Misc → Chamber Parameters → RF Calibration，select Calibration start，in the meanwhile，Current will appear 400 for all

3. 用光筆點 Chamber → Monitor Chamber。將 RF Gen 之 Request 處鍵入"400"。

   Use light pen click Chamber → Monitor Chamber。 For RF Gen’ s Request and enter "400"

4. 觀察 Power Meter 之 Reading 與 Monitor Chamber 下的 Forward 值。若數值很接近 Power etpoint(1 瓦以內)，則不需作做任何動作；如果數值與 Setpoint 有差距，則至 RF Calibration Screen 下 New 欄處做適當調整。之後選擇 Set Calib Constants 將數值輸入。

   To observe Power Meter’ s Reading and Monitor Chamber ‘s Forward value. If the value is close to Power etpoint (within 1W)，and then no action should be taken ；If the value is different with Setpoint，and then adequately adjust in the New column of Calibration Screen of RF. And then select Set Calib Constants and enter the value.

註：降低" FORWARD READING" 或 "Power Meter Reading" 的數值會使原處之讀值升高，反之則讀值降低。

Remark: to decrease the values of " FORWARD READING" or "Power Meter Reading" will make the figure increase; And on the contrary, it will decrease figure.

5. 所有步驟完成後，將 RF CALIBRATION SCREEN 列印下來，即完成 RF 的校正工作。

After complete all the steps and print down the RF CALIBRATION SCREEN. It is complete the RF correction.

四、CHAMBER測漏、復機

CHAMBER' s leak hunting and reboot

1. 低溫測漏：確認 CHAMBER LID ASSEMBLY 已 CLOSE且CHAMBER於 OFFLINE狀態，OPEN ARGON 500~800SCCM，PURGE CHAMBER (0.5~1 HR)後 CLOSE ARGON PURGE，A/B/C/D CHAMBER測漏時，BUFFER CHAMBER 需先VENT至常壓，同時 PM 之 CHAMBER (A/B/C/D), CHAMBER PUMPDOWN至底壓，做1分鐘LEAKAGE測漏。

Low temp leak hunting: confirm CHAMBER LID ASSEMBLY is already close and CHAMBER is OFFLINE condition, OPEN ARGON 500~800SCCM, after PURGE CHAMBER (0.5~1 HR), CLOSE ARGON PURGE, when A/B/C/D CHAMBER leak hunting，BUFFER CHAMBER need to be VENT to normal pressure, in the meantime, PM' s CHAMBER (A/B/C/D) , CHAMBER PUMPDOWN to bottom pressure and apply LEAKAGE leak hunting for 1 min.

原則上低溫測漏前需將 MIXER DIVERT VALVE 作 OUTGASING PURGE PUMPDOWN，測漏 LEAK RATE TREND 必須連續三筆往下 DOWN ，最後一筆須 <3 mTORR ，則可直接作升溫。

Basically, before the low temp leak hunting, it should do MIXER DIVERT VALVE for OUTGASING PURGE PUMPDOWN and leak hunting LEAK RATE TREND must be

continue 3 times drop down and the last time <3 mTORR and then to rise temp directly.

2. 高溫測漏：確認 CHAMBER LID ASSEMBLY 已 CLOSE且 CHAMBER於 OFFLINE狀態，OPEN ARGON 500~800SCCM，PURGE CHAMBER (0.5~1 HR)後 CLOSE ARGON PURGE，A/B/C/D CHAMBER測漏時，BUFFER CHAMBER 需先VENT至常壓，同時 PM 之 CHAMBER (A/B/C/D), CHAMBER PUMPDOWN至底壓，做1分鐘LEAKAGE 測漏。

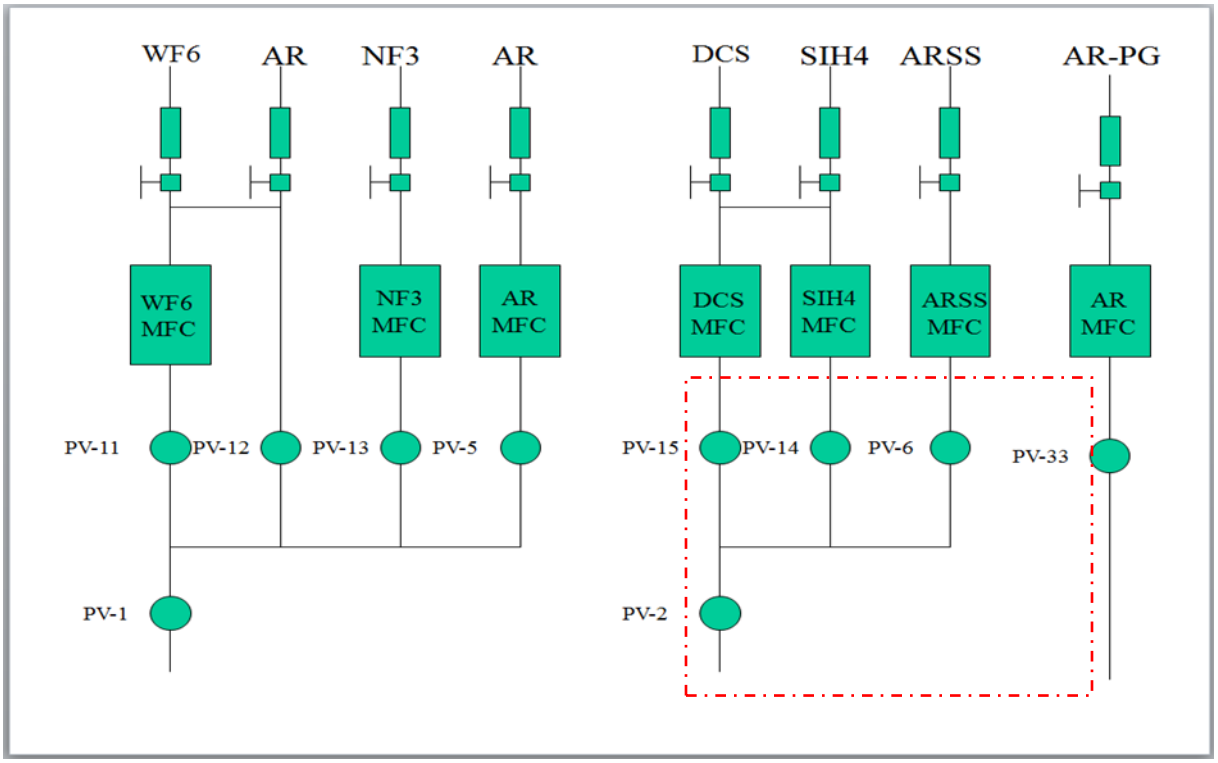
   High temp leak hunting: confirm CHAMBER LID ASSEMBLY is already CLOSE and CHAMBER is OFFLINE condition, OPEN ARGON 500~800SCCM，after PURGE CHAMBER (0.5~1 HR) CLOSE ARGON PURGE, when A/B/C/D CHAMBER is leak hunting, BUFFER CHAMBER need to be vent to normal pressure, in the meantime PM’ s CHAMBER (A/B/C/D), CHAMBER PUMPDOWN to bottom pressure，LEAKAGE leak hunting for 1 min。

3. CHAMBER 升溫至400度 → CHAMBER SERVICE →升溫 LEAK UP START(高溫測漏必須 <1 mTORR) →測漏 OK →設備於高溫測漏後 SIH4 gas pump down→ 關 SIH4 MFC 上方 manual valve，空測 SIH4 gas line PTC (ARSS : 300、SUSCEPTOR : process position、時間 : 3 min)，紀錄 PTC。 PTC < 50 顆 → 交 S100 S/U，並將空測 SIH4 line PTC 記錄在該次 PM之PM table 表單內， 依復機 O.I測機。

   After the equipment leaks at high temperature, SIH4 gas pump down→ Off SIH4 MFC upper manual valve, blank measurement SIH4 gas line PTC (ARSS: 300, SUSCEPTOR: process position, time: 3 min), record PTC. PTC <50 → S100 S/U, and record the blank SIH4 line PTC in the PM PM table form, according to the machine O.I.

4. PM完成後測漏至SiH4 MFC 手動閥，確認閥組有無外漏(如附圖)。

   After the PM is completed, it is leaked to the SiH4 MFC manual valve to check whether the valve group leaks (see the attached drawing)



捌、附件 attachment：

P5200 CENTURA P.M. 記錄表。 (表單編號：G3363-0900-01-××)

P5200 CENTURA P.M. record sheet。 (Sheet no.：G3363-0900-01-××)

玖、生效與修訂 Activating and modify

本規範之公佈實施及其修訂核准層級皆依會簽/核決/分發依循範例為之。

The announcement, implement, revise and approval level of regulations are depend on conference memorandum / approval issues/ distributing are according to criteria examples.

拾、填寫說明：

Fill explanation

一、將 PM 資料輸入並存檔於 EMS 電腦系統中。

Entry PM data and save file in EMS computer system

二、當 EMS 系統無法使用，以紙張填寫。

Fill data by paper when EMS system are not available

附件一 attachment 1

P5200 CENTURA P.M. 記錄表

P5200 CENTURA P.M. record

日期： 執行者： 審核人：

Date: Executor: Approved by:

項次 item	項　　目 item	註記	說　　明 explanation
0	PM Chamber		"C" CLEAN，"*" 更換新品，"#" IPA 擦拭 "C" CLEAN，"*" change new one，"#" wipe by IPA
1	WAFER 片數 WAFER pieces		"OK" 檢查或調整完畢 "OK" check or adjust complete
2	GAS BOX ASSEMBLY		
3	CHAMBER WALL		2-3項:以 IPA 擦拭，請填 "#" Item 2-3: to wipe by IPA and fill "#
4	TUBE GAS FEED		4項:QUARTZ 清洗，請填 "C" Item 4:QUARTZ clean and fill "C"
5	LEVELING		
6	SPACING		
7	WAFER TRANSFER		5-7項:檢查或調整，請填 "OK" Item 5-7: check or adjustment and fill "ok"
8	QUARTZ WINDOW		8項:更換請填 "*"，否則填 "/" Item 8:replacement and fill "*"，if not, fill "/"
9	CHAMBER LID O-RING		
10	SLIT VALVE O-RING		9-10項:視情況更換新品，若未換須以IPA擦拭 Item 9-10: depend on its condition and change to new one. If did not change to new one and shall be wipe by IPA.
11	LAMP MODULE		11項:CHECK LAMP，請填 "OK" Item 11 : CHECK LAMP and fill "OK"
12	BUFFER CHAMBER (convectron) 底壓 BUFFER CHAMBER (convectron) bottom pressure		12項:CHECK 底壓，須 < 120 mT Item 12:CHECK bottom pressure，must be < 120 mT
13	BUFFER CHAMBER LEAK		13項:CHECK 漏率，須 < 10 mT/min(分鐘)

			Item 13:CHECK leaking rate，must be < 10 mT/min
14	CHECK METAL CASSETTE		14項:更換請填 "*"，否則填 "OK" Item 14:change to new one and fill "*"，if not, fill "OK"
15	T/C WAFER MONITOR CHAMBER TEMPERATURE		15項：請記錄CHAMBER ACTUAL TEMPERATURE Item 15: please record CHAMBER ACTUAL TEMPERATURE
16	LOADLOCK CHAMBER A 底壓 LOADLOCK CHAMBER A bottom pressure		16項:CHECK 底壓，須 < 120 mT Item 16:CHECK bottom pressure，must be < 120 Mt
17	LOADLOCK CHAMBER B 底壓 LOADLOCK CHAMBER B bottom pressure		17項:CHECK 底壓，須 < 120 mT Item 17:CHECK bottom pressure，must be < 120 mT
18	LOADLOCK CHAMBER A LEAK		18項:CHECK 漏率，須 < 10 mT/min(分鐘) Item 18:CHECK leaking rate，must be < 10 mT/min
19	LOADLOCK CHAMBER B LEAK		19項:CHECK 漏率，須 < 10 mT/min(分鐘) 19:CHECK leaking rate，must be < 10 mT/min
20	CHAMBER A 底壓 CHAMBER A bottom pressure		20-23項:填寫CHAMBER 底壓 Item 20-23: fill CHAMBER bottom pressure
21	CHAMBER B 底壓 CHAMBER B bottom pressure		24項：填寫 C0值 Item 24：fill C0值
22	CHAMBER C 底壓 CHAMBER C bottom pressure		25項：請填寫CHAMBER WATER FLOW STATUS Item 25：please fill CHAMBER WATER FLOW STATUS
23	CHAMBER D 底壓 CHAMBER D bottom pressure		正常請填寫 "OK" If normal, please fill "OK"
24	請記錄 C0值 Please record C0 value		
25	CHECK CHAMBER LID WATER FLOW		
26	FLAT CHAMBER LEFT ARM O-RING		26-27項:視情況更換新品，若未換須以IPA擦拭 Item 26-27: according to its condition and replace to new one. If it did not change to new one and shall be wipe by IPA.

27	FLAT CHAMBER ORIENT PAD O-RING		
28	PM 前空測 SIH4 LINE PTC 數 Pre-PM PM SIH4 LINE PTC count		28-29項：請填寫PTC 實際數量 Item 28-29 please record PTC count
29	PM 後空測 SIH4 LINE PTC 數 Number of post-PM airborne SIH4 LINE PTCs		
30	CHECK PUMP 底壓 CHAMBER pump pressure		30 項：請填寫 PUMP實際壓力須<50mtorr 30: fill CHAMBER pump pressure<50mtorr

表單編號：G3363-0900-01-M

附件一~一

P5200 CENTURA P.M. 記錄表

日期：(A)　　執行者：(B)　　審核人：(C)

項次	項　　目	註記	說　　明
0	PM Chamber	D	"C" CLEAN，"*" 更換新品，"#" IPA 擦拭 "C" CLEAN，"*" change new one，"#" wipe by IPA
1	WAFER 片數	E	"OK" 檢查或調整完畢 "OK" check or adjust complete
2	GAS BOX ASSEMBLY	F	
3	CHAMBER WALL	F	2-3項:以 IPA 擦拭，請填 "#" Item 2-3: to wipe by IPA and fill "#
4	TUBE GAS FEED	F	4項:QUARTZ 清洗，請填 "C" Item 4:QUARTZ clean and fill "C"
5	LEVELING	F	
6	SPACING	F	
7	WAFER TRANSFER	F	5-7項:檢查或調整，請填 "OK" Item 5-7: check or adjustment and fill "ok"
8	QUARTZ WINDOW	F	8項:更換請填 "*"，否則填 "/" Item 8:replacement and fill "*"，if not, fill "/"
9	CHAMBER LID O-RING	F	
10	SLIT VALVE O-RING	F	9-10項:視情況更換新品，若未換須以IPA擦拭 Item 9-10: depend on its condition and change to new one. If did not change to new one and shall be wipe by IPA.
11	LAMP MODULE	F	11項:CHECK LAMP，請填 "OK" Item 11 : CHECK LAMP and fill "OK"
12	BUFFER CHAMBER (convectron) 底壓	F	12項:CHECK 底壓，須 < 120 mT Item 12:CHECK bottom pressure，must be < 120 mT
13	BUFFER CHAMBER LEAK	F	13項:CHECK 漏率，須 < 10 mT/min(分鐘) Item 13:CHECK leaking rate，must be < 10 mT/min
14	CHECK METAL CASSETTE	F	14項:更換請填 "*"，否則填 "OK"

			Item 14:change to new one and fill "*"，if not, fill "OK"
15	T/C WAFER MONITOR CHAMBER TEMPERATURE	F	15項：請記錄CHAMBER ACTUAL TEMPERATURE Item 15: please record CHAMBER ACTUAL TEMPERATURE
16	LOADLOCK CHAMBER A 底壓 LOADLOCK CHAMBER A bottom pressure	F	16項:CHECK 底壓，須 < 120 mT Item 16:CHECK bottom pressure，must be < 120 Mt
17	LOADLOCK CHAMBER B 底壓 LOADLOCK CHAMBER B bottom pressure	F	17項:CHECK 底壓，須 < 120 mT Item 17:CHECK bottom pressure，must be < 120 mT
18	LOADLOCK CHAMBER A LEAK	F	18項:CHECK 漏率，須 < 10 mT/min(分鐘) Item 18:CHECK leaking rate，must be < 10 mT/min
19	LOADLOCK CHAMBER B LEAK	F	19項:CHECK 漏率，須 < 10 mT/min(分鐘) 19:CHECK leaking rate，must be < 10 mT/min
20	CHAMBER A 底壓 CHAMBER A bottom pressure	G	20-23項:填寫CHAMBER 底壓 Item 20-23: fill CHAMBER bottom pressure
21	CHAMBER B 底壓 CHAMBER B bottom pressure	F	24項：填寫 C0值 Item 24：fill C0值
22	CHAMBER C 底壓 CHAMBER C bottom pressure	F	25項：請填寫CHAMBER WATER FLOW STATUS Item 25：please fill CHAMBER WATER FLOW STATUS
23	CHAMBER D 底壓 CHAMBER D bottom pressure	F	正常請填寫 "OK" If normal, please fill "OK"
24	請記錄 C0值 Please record C0 value	F	
25	CHECK CHAMBER LID WATER FLOW	F	
26	FLAT CHAMBER LEFT ARM O-RING	F	26-27項:視情況更換新品，若未換須以IPA擦拭 Item 26-27: according to its condition and replace to new one. If it did not change to new one and shall be wipe by IPA.
27	FLAT CHAMBER ORIENT PAD O-RING	F	
28	PM 前空測 SIH4 LINE PTC 數 Pre-PM PM SIH4 LINE PTC count	H	28-29項：請填寫PTC 實際數量 Item 28-29 please record PTC count

29	PM 後空測 SIH4 LINE PTC 數 Number of post-PM airborne SIH4 LINE PTCs	H	
30	CHECK PUMP 底壓 CHAMBER pump pressure	I	30 項：請填寫 PUMP實際壓力須<50mtorr 30: fill CHAMBER pump pressure<50mtorr

表單編號：G3363-0900-01-M

附件一~二

表格填寫說明

Fill explanation

表格名稱: P5200 CENTURA P.M. 記錄表

Sheet : P5200 CENTURA P.M. record

項目 item	欄位名稱 Column	填寫方式及內容 Fill method and content
A	年/月份 year/month	填寫執行日期 executive date
B	執行者 executor	負責機台 PM，執行者簽名 In charge of machine PM and sign by executor
C	審核人 auditor	主管或指定審核人檢查後簽名 Supervisor or auditor sign after check
D	PM CHAMBER NAME	請填寫 “A” or ” B” or ” C” or ” D” Please fill “A” or ” B” or ” C” or ” D”
E	片數 piece	請填入 PM 時之片數 Please fill with pieces when PM
F	執行項目 executive item	依說明欄之代表符號填寫 According to explanation column and fill with represent symbol
G	記錄 C0值 record C0 value	請填寫記錄值 Please fill with record value
H	記錄 PTC數值 Record PTC value	請填寫檢測記錄值 Please fill with record value
I	記錄 PUMP 底壓 Record pump base pressure	請填寫 PUMP實際壓力 Please fill in the actual pressure of PUMP